Small Signal MOSFET

20 V, 915 mA, Single N-Channel with ESD Protection, SC-75 and SC-89

Features

- Low R_{DS(on)} Improving System Efficiency
- Low Threshold Voltage, 1.5 V Rated
- ESD Protected Gate
- NV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- Pb-Free Packages are Available

Applications

- Load/Power Switches
- Power Supply Converter Circuits
- Battery Management
- Portables like Cell Phones, PDAs, Digital Cameras, Pagers, etc.

MAXIMUM RATINGS (T_J = 25°C unless otherwise stated)

Parame	Symbol	Value	Units		
Drain-to-Source Voltage	V_{DSS}	20	V		
Gate-to-Source Voltage	V_{GS}	±6.0	V		
Continuous Drain Steady T _A = 25°C			I _D	915	mA
Current (Note 1)	urrent (Note 1) State $T_A = 85^{\circ}C$			660	
Power Dissipation (Note 1)	Stea	dy State	P _D	300	mW
Pulsed Drain Current	t _p =	=10 μs	I _{DM}	1.3	Α
Operating Junction and St	T _J , T _{STG}	–55 to 150	°C		
Continuous Source Currer	IS	280	mA		
Lead Temperature for Solo (1/8" from case for 10 s)	TL	260	°C		

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Value	Units
Junction-to-Ambient - Steady State (Note 1) SC-75 / SOT-416 SC-89	$R_{\theta JA}$	416 400	°C/W

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

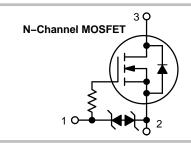
1. Surface mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces).



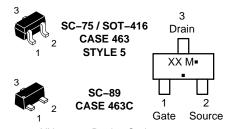
ON Semiconductor®

http://onsemi.com

V _{(BR)DSS} R _{DS(on)} TYP		I _D MAX
20 V	0.127 Ω @ 4.5 V	
	0.170 Ω @ 2.5 V	915 mA
	0.242 Ω @ 1.8 V	31011111
	0.500 Ω @ 1.5 V	



MARKING DIAGRAM & PIN ASSIGNMENT



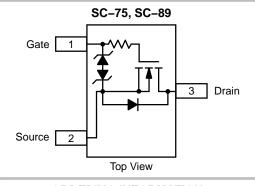
XX = Device Code

M = Date Code*

Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.



ORDERING INFORMATION

See detailed ordering and shipping information on page 4 of this data sheet.

ELECTRICAL CHARACTERISTICS (T₁ = 25°C unless otherwise stated)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS	•		•		•	•	
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D$	20	26		V	
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J				18.4		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V, V_I$	_{OS} = 16 V			100	nA
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{G}$	_S = ±4.5 V			±1.0	μΑ
ON CHARACTERISTICS (Note 2)							
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_{D}$	= 250 μΑ	0.45	0.76	1.1	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-2.15		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 600 \text{ mA}$			127	230	mΩ
		V _{GS} = 2.5 V, I _D	= 500 mA		170	275	7
		V _{GS} = 1.8 V, I _D = 350 mA			242	700	7
	$V_{GS} = 1.5 \text{ V}, I_D = 40 \text{ mA}$		_O = 40 mA		500	950	
Forward Transconductance	9FS	$V_{DS} = 10 \text{ V}, I_D = 400 \text{ mA}$			1.4		S
CHARGES AND CAPACITANCES							
Input Capacitance	C _{ISS}	$V_{GS} = 0 \text{ V, f} = 1.0 \text{ MHz,}$ $V_{DS} = 16 \text{ V}$			110		pF
Output Capacitance	C _{OSS}				16		
Reverse Transfer Capacitance	C _{RSS}				12		
Total Gate Charge	$Q_{G(TOT)}$				1.82		nC
Threshold Gate Charge	Q _{G(TH)}	$V_{GS} = 4.5 \text{ V, V}$ $I_{D} = 0.2$	_{DS} = 10 V,		0.2		
Gate-to-Source Charge	Q_GS	$I_D = 0.2$	ŽÅ		0.3		
Gate-to-Drain Charge	Q_GD				0.42		
SWITCHING CHARACTERISTICS (No	te 3)						
Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = 4.5 \text{ V}, V_{DD} = 10 \text{ V},$ $I_{D} = 0.2 \text{ A}, R_{G} = 10 \Omega$			3.7		ns
Rise Time	t _r				4.4		
Turn-Off Delay Time	t _{d(OFF)}				25		
Fall Time	t _f				7.6		
DRAIN-SOURCE DIODE CHARACTE	RISTICS						
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V,	T _J = 25°C		0.67	1.1	V
		$I_{S} = 200 \text{ mA}$			0.54		1

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 2. Pulse Test: pulse width $\leq 300~\mu s$, duty cycle $\leq 2\%$.

^{3.} Switching characteristics are independent of operating junction temperatures.

TYPICAL ELECTRICAL CHARACTERISTICS

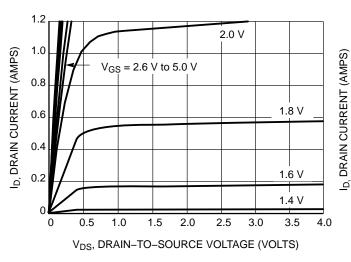


Figure 1. On-Region Characteristics

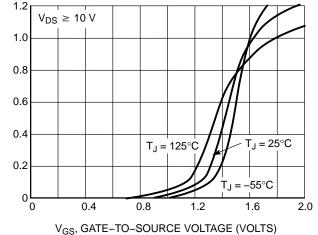


Figure 2. Transfer Characteristics

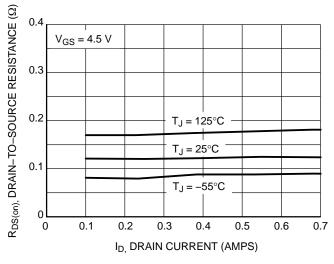


Figure 3. On–Resistance vs. Drain Current and Temperature

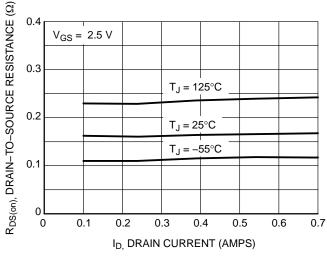


Figure 4. On–Resistance vs. Drain Current and Temperature

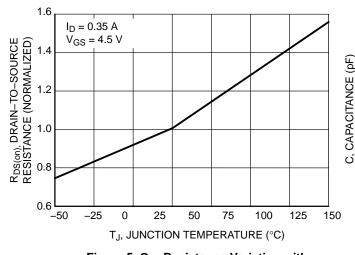


Figure 5. On–Resistance Variation with Temperature

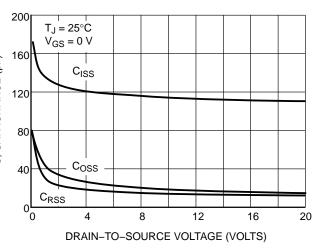
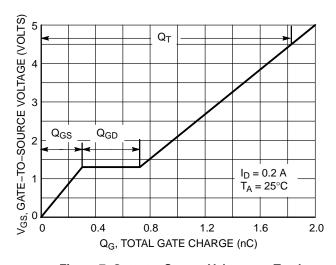


Figure 6. Capacitance Variation

TYPICAL ELECTRICAL CHARACTERISTICS



O.6 O.6 O.5 O.5

Figure 7. Gate-to-Source Voltage vs. Total Gate Charge

Figure 8. Diode Forward Voltage vs. Current

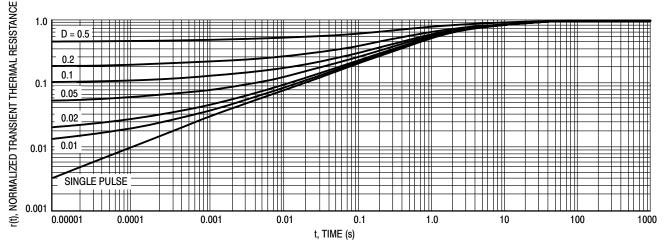


Figure 9. Normalized Thermal Response

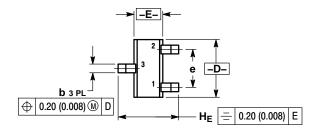
ORDERING INFORMATION

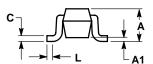
Device	Marking	Package	Shipping [†]		
NTA4153NT1	TR	SC-75 / SOT-416	3000 / Tape & Reel		
NTA4153NT1G	TR	SC-75 / SOT-416 (Pb-Free)	3000 / Tape & Reel		
NTE4153NT1G	TP	SC-89 (Pb-Free)	3000 / Tape & Reel		
NVA4153NT1G	VR	SC-75 / SOT-416 (Pb-Free)	3000 / Tape & Reel		
NVE4153NT1G	VP	SC-89 (Pb-Free)	3000 / Tape & Reel		

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SC-75/SOT-416 **CASE 463** ISSUE F



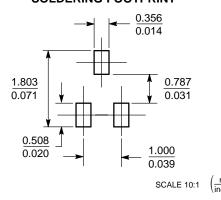


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.70	0.80	0.90	0.027	0.031	0.035	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
b	0.15	0.20	0.30	0.006	0.008	0.012	
С	0.10	0.15	0.25	0.004	0.006	0.010	
D	1.55	1.60	1.65	0.059	0.063	0.067	
Е	0.70	0.80	0.90	0.027	0.031	0.035	
е	1.00 BSC				0.04 BSC		
L	0.10	0.15	0.20	0.004	0.006	0.008	
He	1.50	1.60	1.70	0.061	0.063	0.065	

STYLE 5: PIN 1. GATE 2. SOURCE 3. DRAIN

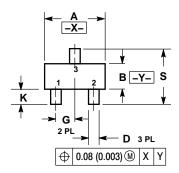
SOLDERING FOOTPRINT*

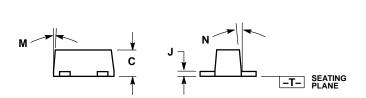


*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SC-89 CASE 463C-03 **ISSUE C**



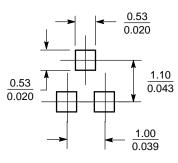


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL
- 463C-01 OBSOLETE, NEW STANDARD 463C-02.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	1.50	1.60	1.70	0.059	0.063	0.067	
В	0.75	0.85	0.95	0.030	0.034	0.040	
С	0.60	0.70	0.80	0.024	0.028	0.031	
D	0.23	0.28	0.33	0.009	0.011	0.013	
G	0.50 BSC			0.020 BSC			
Н	0.53 REF			0.021 REF			
J	0.10	0.15	0.20	0.004	0.006	0.008	
K	0.30	0.40	0.50	0.012	0.016	0.020	
L	1.10 REF			0.043 REF			
М			10 °			10 °	
Ν			10 °			10 °	
S	1.50	1.60	1.70	0.059	0.063	0.067	

SOLDERING FOOTPRINT*



mm **SCALE 10:1**

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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